

Supporting Information

Ultrasensitive, Ultrafast and Gate-Tunable Two-Dimensional Photodetectors in Ternary Rhombohedral ZnIn₂S₄ for Optical Neural Networks

Weili Zhen^{ab§}, Xi Zhou^{de§}, Shirui Weng^a, Wenka Zhu^{a*}, and Changjin Zhang^{ac†}

^a*High Magnetic Field Laboratory, Chinese Academy of Sciences, Hefei 230031, China*

^b*University of Science and Technology of China, Hefei 230026, China*

^c*Institutes of Physical Science and Information Technology, Anhui University, Hefei 230601, China*

^d*The Interdisciplinary Research Center, Shanghai Advanced Research Institute, Chinese Academy of Sciences, Shanghai 201210, China*

^e*School of Microelectronics, University of Chinese Academy of Sciences, Beijing 100049, China*

*Email: wkzhu@hmfl.ac.cn

†Email: zhangcj@hmfl.ac.cn

§W.Z. and X.Z. contributed equally to this paper

1. Figures and tables

1.1. Schematic diagram of CVT growth of R-ZIS single crystals and an optical image

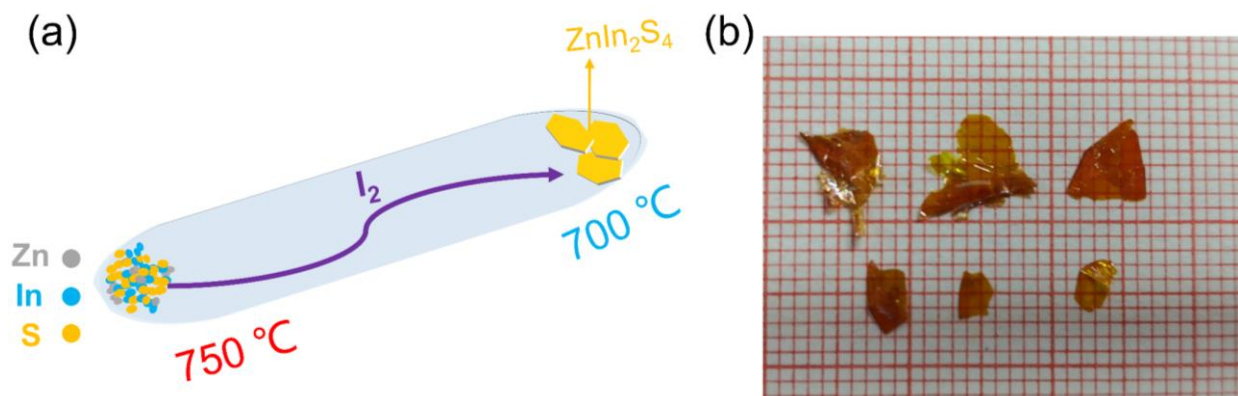


Figure S1. (a) Schematic diagram of chemical vapor transport growth of R-ZIS single crystals. (b) An optical image of the as-grown R-ZIS single crystals. The size of each small grid is 1×1 mm².

1.2. Powder XRD pattern

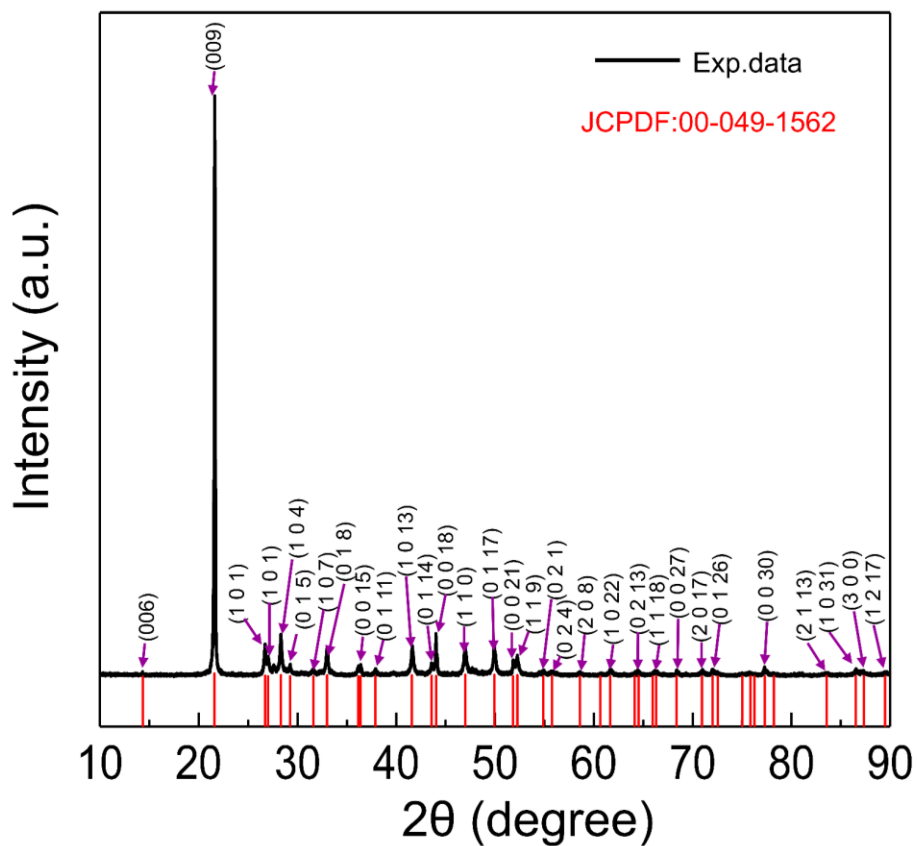


Figure S2. Powder XRD pattern of R-ZIS. The red ticks indicate the positions of the diffractions

1.3. Optical image showing more R-ZIS flakes

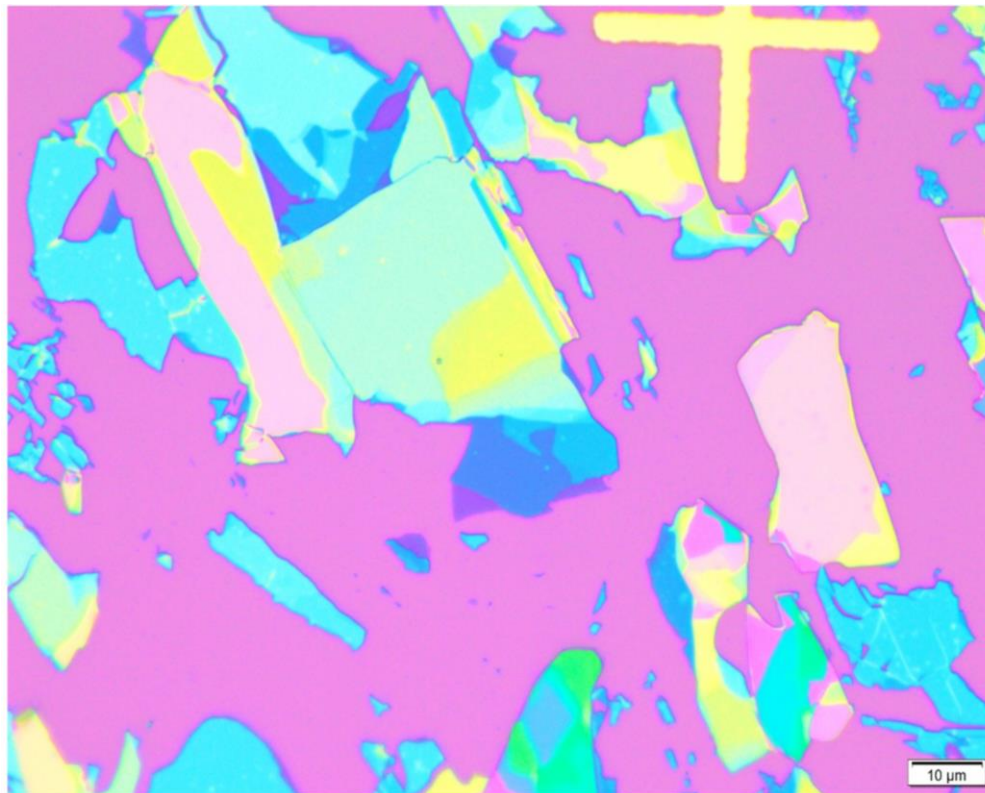


Figure S3. Optical image of R-ZIS flakes on SiO₂/Si substrate. Different optical contrasts correspond to different thicknesses and layers.

1.4. SAED pattern and HRTEM image taken on the cross section of an R-ZIS thin flake prepared by focused ion beam

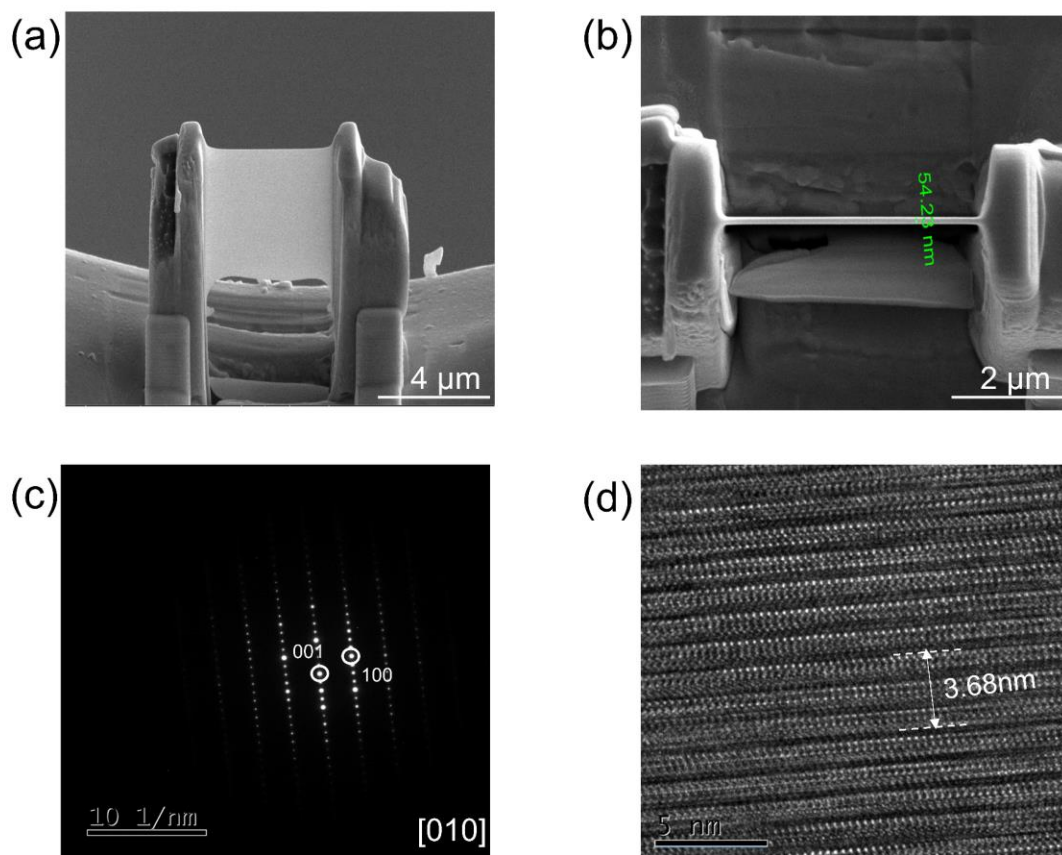


Figure S4. (a) R-ZIS thin flake prepared by focused ion beam. (b) Cross-sectional view of the R-ZIS sheet. The thickness is about 54 nm. (c) SAED pattern taken on the sample shown in (a) and (b). The diffraction spots correspond to the [001] and [100] crystallographic planes. The zone axis is [010]. (d) HRTEM image. The interplanar spacing is determined to be about 3.68 nm, which is close to the lattice parameter $c = 3.7$ nm.

1.5. STEM-EDX spectrum

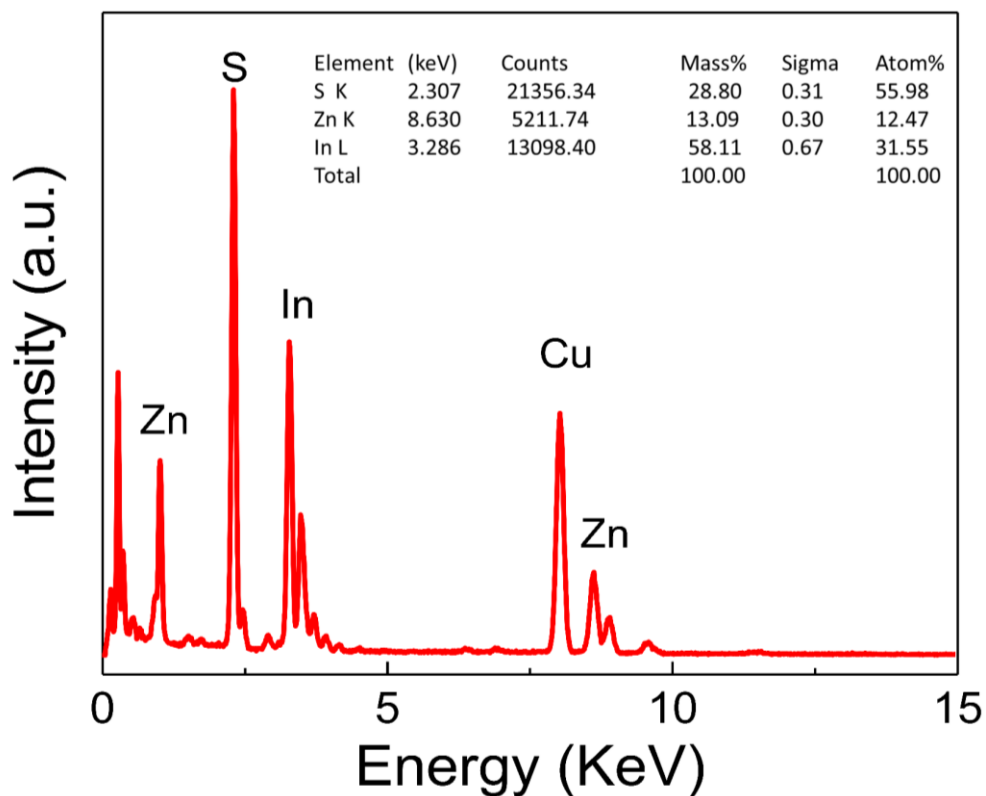


Figure S5. STEM-EDS spectrum of R-ZIS flake. The atomic ratio is close to 1:2:4.

1.6. Optical image and I – V curves of R-ZIS photodetector based on Cr/Au contact

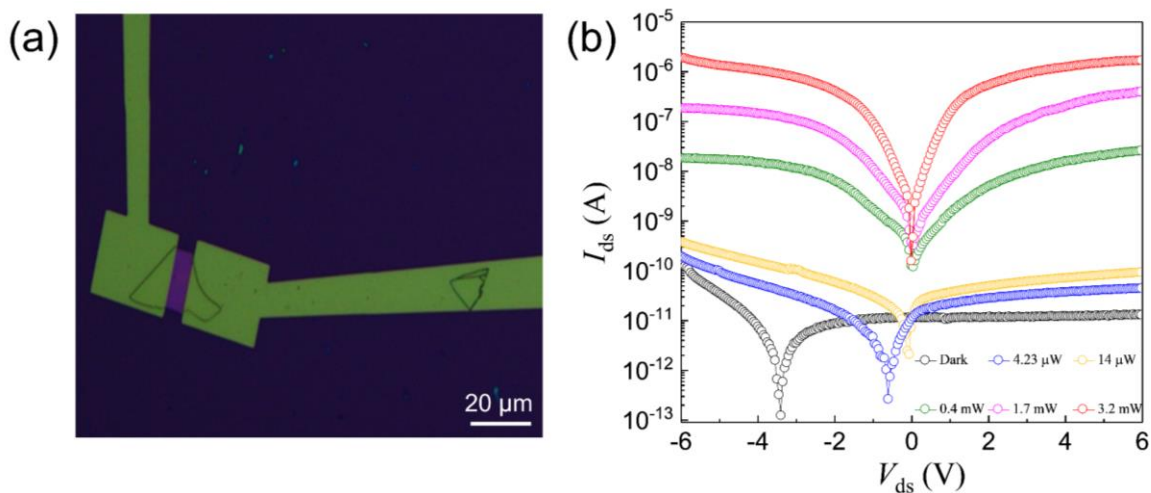


Figure S6. (a) Optical image of R-ZIS photodetector based on Cr/Au contact. The scale bar is 20 μm . (b) $I_{\text{ds}}-V_{\text{ds}}$ characteristics taken in the dark and under a 405 nm laser tuned to different laser

powers.

1.7. Time-resolved photocurrent of R-ZIS photodetector taken under lasers of different wavelength

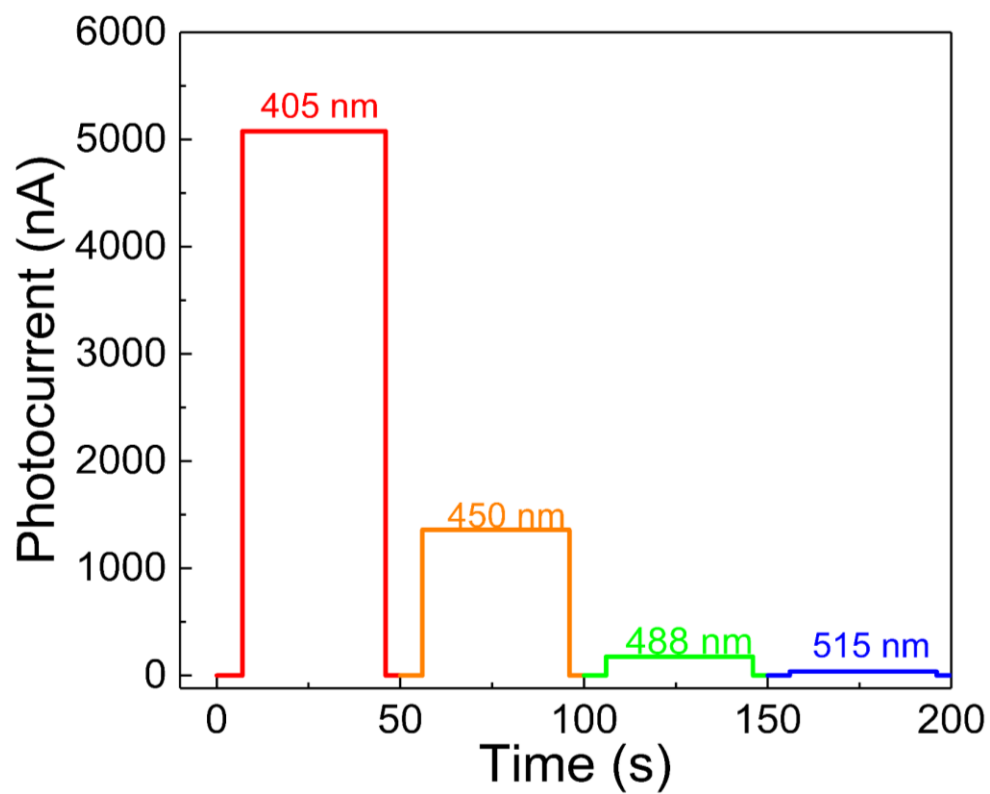


Figure S7. Time-resolved photocurrent of R-ZIS photodetector taken under lasers of different wavelength (405 nm, 450 nm, 488 nm and 515 nm) at $V_{ds} = 5$ V and 5.3 mW.

1.8. I – V curve taken under illumination of 370 nm

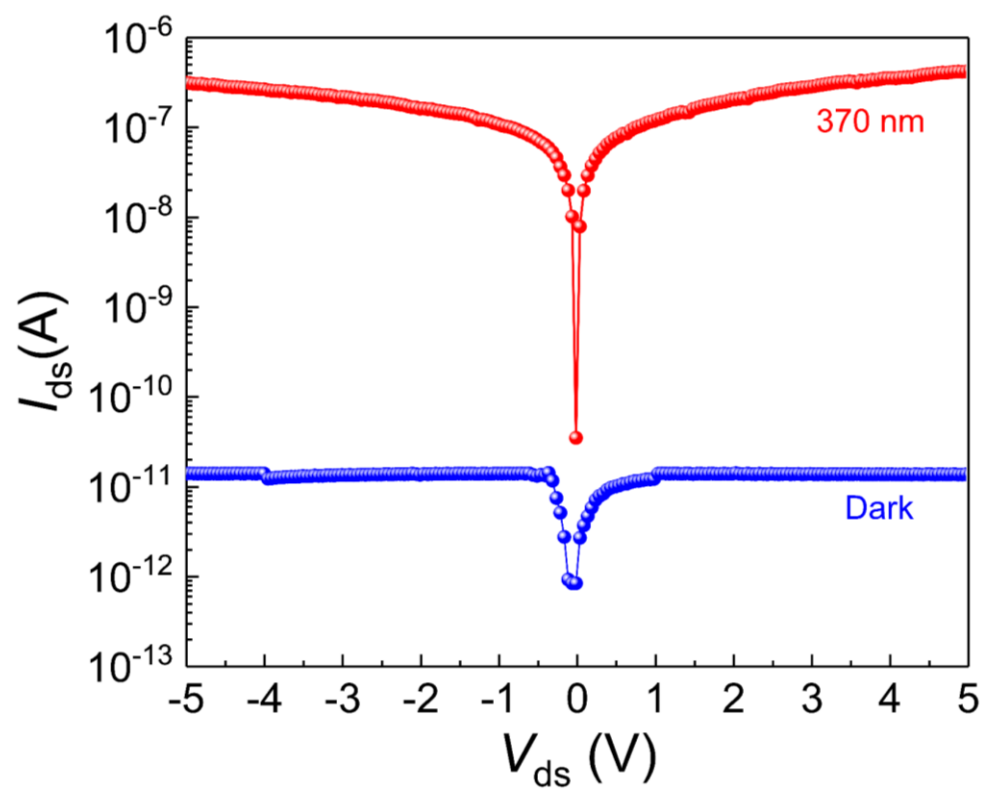


Figure S8. Semi-logarithmic I_{ds} – V_{ds} characteristics taken in the dark and under illumination of 370 nm.

1.9. Test results of more devices (S2 and S3)

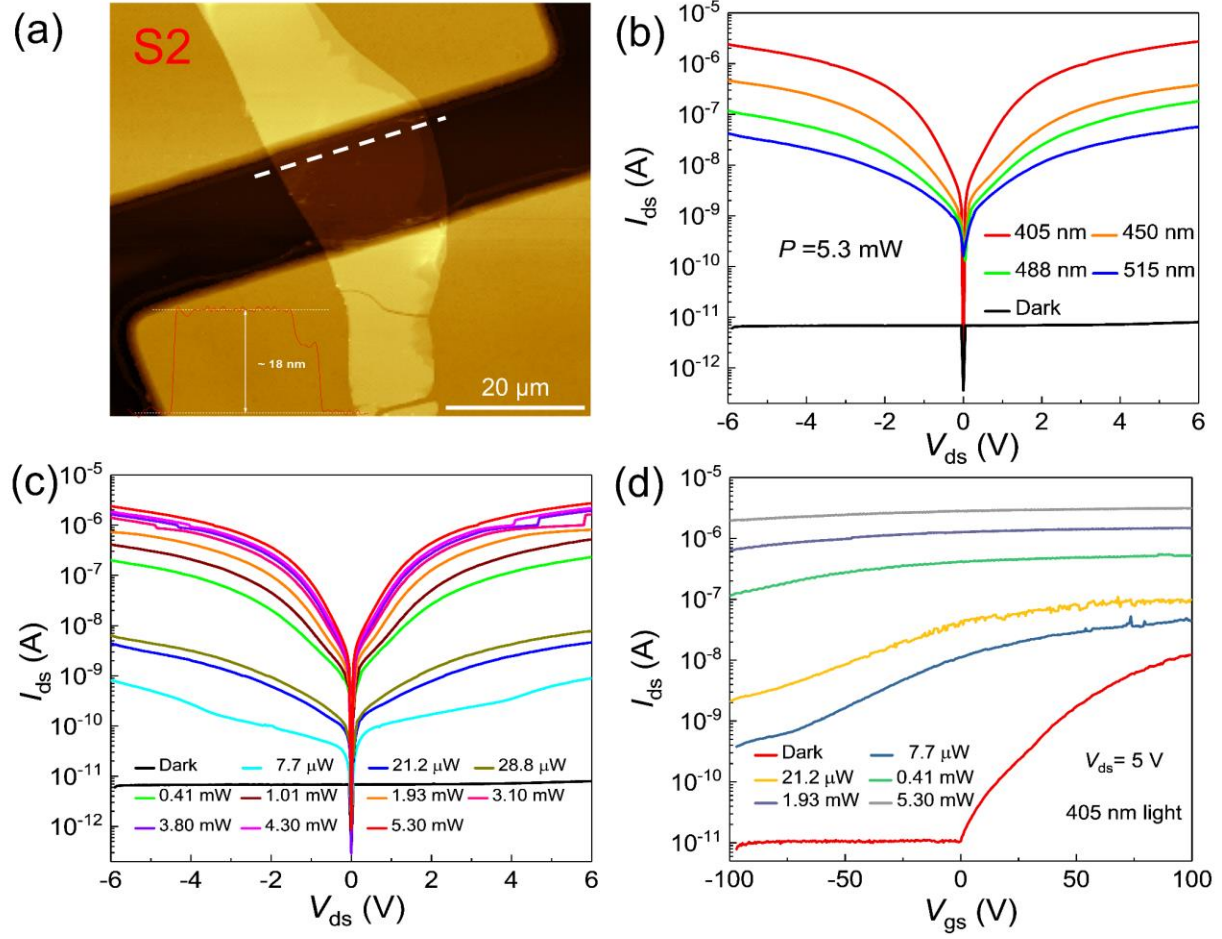


Figure S9. (a) AFM image of device S2. The thickness of R-ZIS flake is about 18 nm. The scale bar is 20 μm. (b) Semi-logarithmic I_{ds} - V_{ds} curves taken in the dark and under illumination of different wavelengths. The laser power is tuned to 5.3 mW. (c) I_{ds} - V_{ds} curves taken in the dark and under a 405 nm laser tuned to different powers. (d) Transfer curves at $V_{ds} = 5$ V under the 405 nm laser.

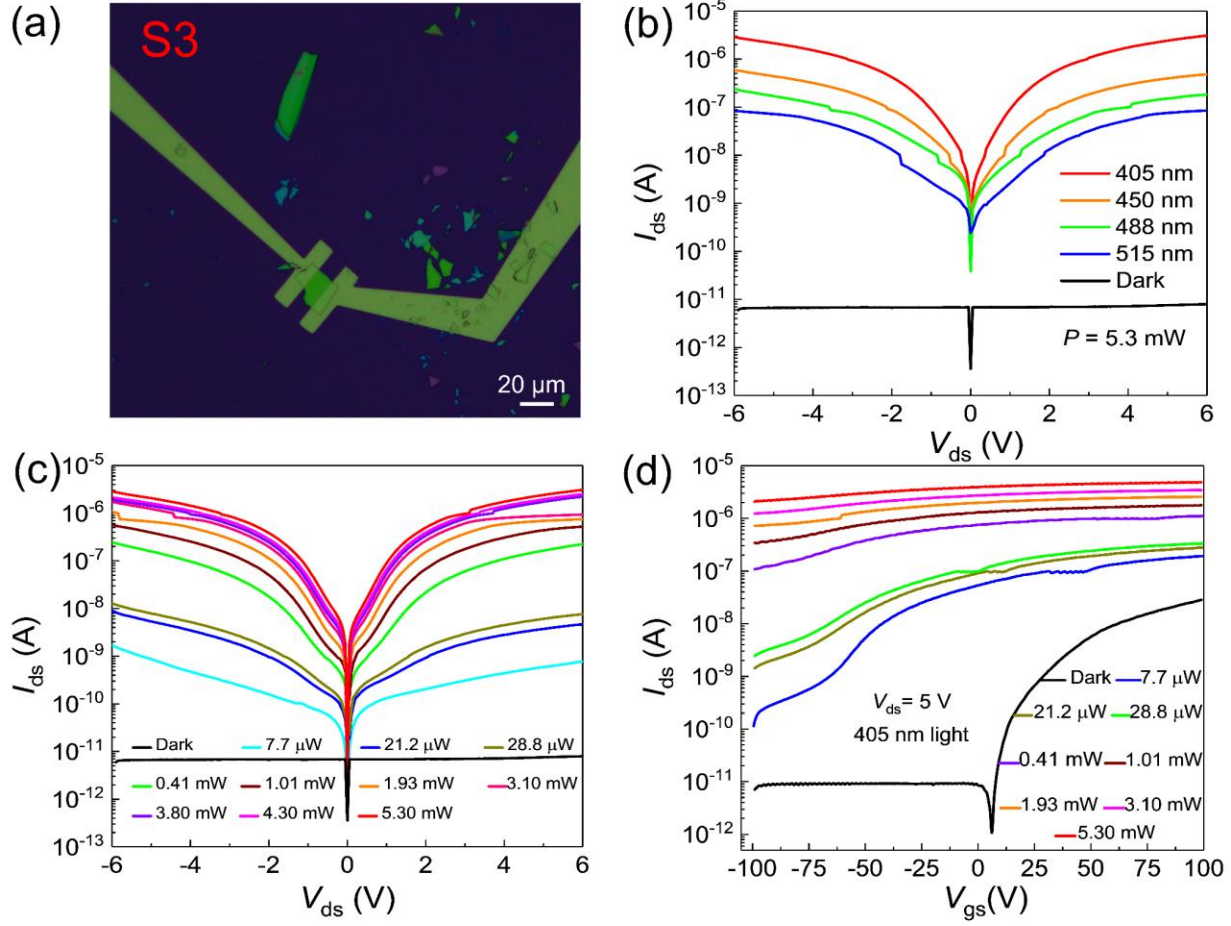


Figure S10. (a) Optical image of device S3. The scale bar is 20 μm. (b) Semi-logarithmic I_{ds} – V_{ds} curves taken in the dark and under illumination of different wavelengths. The laser power is tuned to 5.3 mW. (c) I_{ds} – V_{ds} curves taken in the dark and under a 405 nm laser tuned to different powers. (d) Transfer curves at $V_{ds} = 5$ V under the 405 nm laser.

1.10. Diagram of optoelectronic measurement setup

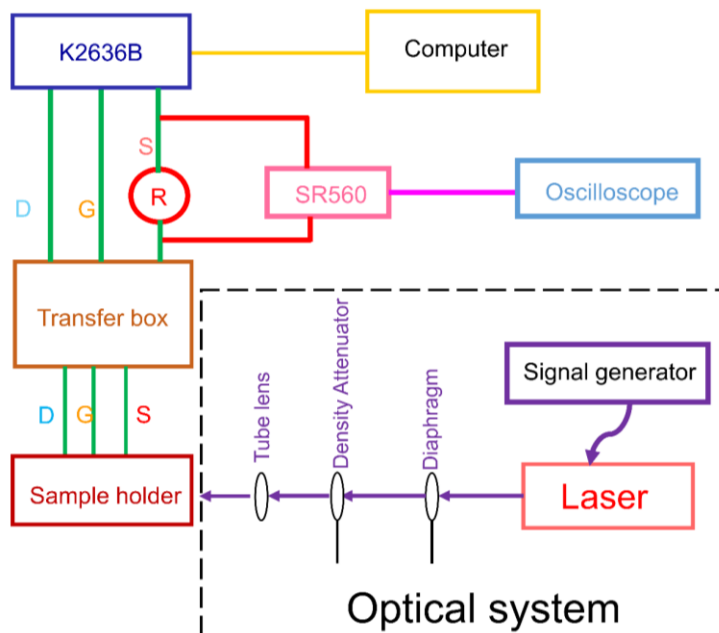


Figure S11. Diagram of optoelectronic measurement setup. The incident laser is produced by a fiber-coupled laser and the frequency of the laser can be changed by an external arbitrary signal generator (Tektronix AFG31021). The power of illumination laser is determined by a power and energy meter (Laser Power Meter LP10, Sanwa), and electrodes of the device are connected to a semiconductor device analyzer (Keithley 2636B) equipped with a homemade transfer box. The current signal is converted to a voltage signal using a resistance box, and then the voltage signal is passed to the preamp (Stanford Research System, SR560). Finally, the output voltage (from SR560) is displayed on an oscilloscope (Tektronix MDO3014).

1.11. Comparison of photoresponse characteristics of R-ZIS with some reported photodetectors based on 2D materials

Table S1. Comparison of photoresponse characteristics of ZIS with some reported photodetectors based on 2D materials.

| Material | Laser (nm) | V_{bias} (V) | V_g (V) | I_{dark} (nA) | R (A W^{-1}) | D^* (Jones) | τ_{rise} (ms) | τ_{decay} (ms) |
|---|---------------|--------------------------|--------------|---------------------------|------------------------------|-----------------------|------------------------------|-------------------------------|
| InSe ¹ | 450 | 10 | 70 | 2000 | 157 | $<10^{12}$ | 50 | 4×10^3 |
| ReSe ₂ ² | 633 | 0.5 | 0 | 2.5 | 95 | - | 68 | 34 |
| SnS ₂ ³ | 350 | 1 | 20 | 525 | 400 | - | 20 | 16 |
| GaSe ⁴ | 380 | 4 | 0 | 0.5 | 2.6 | 1.0×10^{12} | 2.37×10^4 | 6.3×10^3 |
| Si ₂ Te ₃ ⁵ | 450 | 1 | 40 | 0.08 | 27 | 2.8×10^{12} | 210 | 478 |
| NiPS ₃ ⁶ | 245 | 10 | 0 | $<10^{-5}$ | 0.13 | 1.2×10^{12} | 3.2 | 17.2 |
| MnPS ₃ ⁷ | 365 | 8 | 70 | 1.4×10^{-3} | 288 | 6.48×10^{11} | 340 | 600 |
| Ta ₂ NiSe ₅ ⁸ | 808 | 0.1 | 0 | 4500 | 17.21 | - | 3000 | 3300 |
| Ga ₂ In ₄ S ₉ ⁹ | 360 | 5 | 0 | 0.5 | 112 | 2.25×10^{11} | 40 | 50 |
| R-ZnIn ₂ S ₄ (This work) | 405 | 5 | 0 | 7×10^{-3} | 230 | 1.8×10^{14} | 0.22 | 0.158 |
| R-ZnIn ₂ S ₄ (This work) | 405 | 5 | 70 | 66 | 1.0×10^4 | 3.7×10^{13} | 0.75 | 0.536 |

1.12. Correlation coefficients between the theoretical results and the outputs combining R-ZIS photodetector I – V characteristics

Table S2. Correlation coefficients between the theoretical results and the outputs combining ZIS photodetector I – V characteristics.

| Map number | Kernel 1 | Kernel 2 | Kernel 3 |
|------------|----------|----------|----------|
| II | 0.8192 | 0.9175 | 0.8773 |
| III | 0.9449 | 0.9655 | 0.9564 |
| IV | 0.9598 | 0.9769 | 0.9648 |
| V | 0.9677 | 0.9813 | 0.9767 |

2. Reliability of using TEM to identify atoms in thin flakes

Aberration-corrected scanning transmission electron microscopy (STEM) is an effective tool for characterizing thin-flake samples at the atomic scale. In previous researches, few-layer or monolayer 2D materials were indeed unstable or even damaged under high-energy electron beams with acceleration voltages over 120 kV [PRL, 109, 035503 (2012), Ultramicroscopy 146, 33 (2014)]. However, by lowering the acceleration voltage, typically below 100 kV, the damage caused by the electron beam to the materials can be reduced, allowing the identification of atoms and defects in thin materials. This has been achieved in many few-layer and monolayer 2D materials, such as MoS₂ [Adv. Mater. 26, 2857 (2014), Adv. Mater. 26, 2648 (2014)], WSe₂ [Chem. Mater. 33, 1307 (2021), Adv. Mater. 2022, 2106551, Nat. Phys. 17, 92 (2021)], MoTe₂ [ACS Nano 11, 11005 (2017)], InSe [ACS Nano 13, 5112 (2019)], GaSe [ACS Nano 9, 8078 (2015)] and ReS₂ [ACS Nano 9, 11249 (2015)]. These results demonstrate the reliability of this identification.

In addition, for the monolayer and few-layer hexagonal phase ZnIn₂S₄, an isomer of rhombohedral ZnIn₂S₄ in the present work, the identification of atoms and Zn vacancies by STEM has been successfully performed [JACS 139, 7586 (2017), ACS Nano 15, 15238 (2021),

ChemSusChem 14, 852 (2021)]. Based on these experiences, we chose a relatively low acceleration voltage of 80 kV in the STEM experiment, which reduced the damage to the sample and gave satisfactory results. Therefore, the STEM characterization and analysis presented in Figure 2 are reliable.

3. Noise current and dark current

According to previous studies [Science 325,5948 (2009)], the total noise of photodetectors operating in DC and low frequency modes consists of two main components, thermal noise and shot noise. The shot noise originates from dark current. Their contributions can be estimated by calculations using the following parameters, $I_{\text{dark}} = 7 \text{ pA}$, $V_{\text{ds}} = 5 \text{ V}$ and $T = 300 \text{ K}$.

The thermal noise is calculated as

$$i_{\text{thermal}} = \sqrt{\frac{4k_B T}{R}} = \sqrt{\frac{4 \times 1.38 \times 10^{-23} \times 300}{7.14 \times 10^{11}}} \text{ A Hz}^{-1/2} = 1.52 \times 10^{-16} \text{ A Hz}^{-1/2},$$

where k_B is the Boltzmann constant and R is the channel resistance of the device.

The shot noise is calculated as

$$i_{\text{shot}} = \sqrt{2eI_{\text{dark}}} = \sqrt{2 \times 1.6 \times 10^{-19} \times 7 \times 10^{-12}} \text{ A Hz}^{-1/2} = 1.5 \times 10^{-15} \text{ A Hz}^{-1/2},$$

where e is the elementary charge.

Thus, the total noise current is

$$i_{\text{total}} = \sqrt{i_{\text{thermal}}^2 + i_{\text{shot}}^2} = \sqrt{(1.52 \times 10^{-16})^2 + (1.5 \times 10^{-15})^2} \text{ A Hz}^{-1/2} = 1.507 \times 10^{-15} \text{ A Hz}^{-1/2} \approx i_{\text{shot}}.$$

From the calculations, it is found that the shot noise is one order of magnitude larger than the thermal noise. The shot noise is the major contribution to the total noise. Therefore, it is reasonable and safe to use I_{dark} instead of the total noise current to calculate D^* .

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